Claims:

1. A method for manufacturing an object, the method comprising the steps of:

(a) providing a wafer comprising semi-finished objects;

(b) separating said wafer into sub-wafers, at least one of said sub-wafers comprising a plurality of said semi-finished objects;

(c) processing at least a portion of said plurality of semi-finished objects by subjecting said at least one of said sub-wafers to at least one processing step, wherein said at least one processing step is applied to a separation face of said sub-wafer originating from step (b).

2. The method according to claim 1, wherein said portion comprises at least two of said plurality of semi-finished objects.

3. The method according to claim 1, wherein said portion comprises at least half of said plurality of semi-finished objects.

4. A method for manufacturing an object, the method comprising the steps of:

(a) providing a wafer comprising semi-finished objects;

(b) separating said wafer into sub-wafers, at least one of said sub-wafers comprising a plurality of said semi-finished objects;

(c) processing at least a portion of said plurality of semi-finished objects by subjecting said at least one of said sub-wafers to at least one processing step, wherein said at least one processing step comprises creating a slanted side wall

of said sub-wafer slanted with respect to a lateral plane, wherein creating said slanted side wall is accomplished by removing material from said sub-wafer.

5. The method according to claim 4, wherein step (c) is carried out while said plurality of said semi-finished objects is comprised in said sub-wafer.

6. The method according to claim 4, wherein in step (c),

all the semi-finished objects of said portion of said plurality of semi-finished objects are simultaneously processed; or

the semi-finished objects of said portion of said plurality of semi-finished objects are subsequently processed.

7. The method according to claim 4, wherein in step (c), each of said semi-finished objects of said at least one sub-wafer is processed by subjecting said at least one sub-wafer to at least one processing step.

8. The method according to claim 4, wherein each of at least two of said sub-wafers comprises a respective plurality of said semi-finished objects, wherein the method comprises carrying out for each respective one of said at least two sub-wafers, the step of

(c') processing at least a portion of the respective plurality of semi-finished objects of the respective sub-wafer by subjecting the respective sub-wafer to said at least one processing step.

9. The method according to claim 4, wherein in said at least one sub-wafer, said plurality of said semi-finished objects forms a repetitive one-dimensional arrangement of said semi-finished objects.

10. The method according to claim 4, wherein in said at least one sub-wafer, said plurality of said semi-finished objects is arranged along one or two straight lines.

11. The method according to claim 4, wherein said at least one processing step comprises at least one of the group consisting of

a replication step;

a mechanical processing step;

a polishing step;

a grinding step;

a cutting step;

a chemical processing step;

a lithographic step;

a coating step; and

an etching step.

12. The method according to claim 4, wherein said object is at least one of the group consisting of:

an optical element;

an optical device;

a substrate comprising at least one slanted face;

an optical sub-assembly comprising a substrate on which a light emitter is mounted, wherein said substrate on which a light emitter is mounted has at least one slanted face and/or wherein said light emitter is an edge-emitting light emitter and/or a laser;

an opto-electronic module;

an optical system;

a light-guiding device;

a micro-mechanical element;

a micro-electro-mechanical element;

a micro-electro-mechanical system.

13. The method according to claim 4, wherein said wafer is at least partially made of a transparent polymer or of a glass.

14. The method according to claim 4, comprising carrying out, after carrying out step (c), the step of

(d) separating said at least one sub-wafer into a plurality of parts, wherein each part comprises one of said processed semi-finished objects.

15. The method according to claim 4, comprising carrying out, before carrying out step (b), the step of

(e) manufacturing said wafer.